

# High-Performance 100-V GaN Transistor with Integrated Gate Driver

## General description

The CGR1101 is a high-performance and highly reliable 100-V enhancement-mode GaN transistor with integrated gate driver, optimized for high switching frequency applications, including LiDAR, Time-of-Flight (ToF), and power converter. The minimum 1-ns input pulse width makes higher power/current allowable in these applications to improve mapping range and resolution. The extremely small propagation delay of 3.3ns significantly improves the control loop response time and thus overall performance of the power converters. Split output allows the drive strength and switching time to be adjusted through external resistors between OUT+ and OUT-.

The power GaN transistors in CGR1101, have 100-V drain-source blocking voltage and typical  $R_{DS(ON)}$  of 7 m $\Omega$ .

CGR1101 features undervoltage lockout (UVLO) and over-temperature protection (OTP) to ensure the GaN transistor is not damaged in overload or fault conditions.

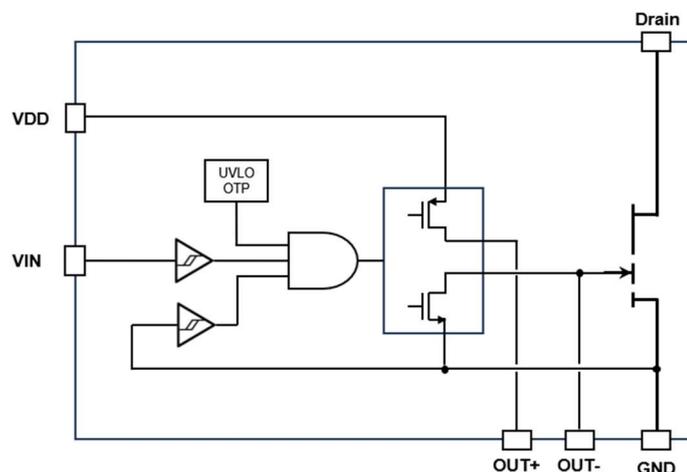
CGR1101 is available in a compact 5 x 6 mm DFN package for a minimized parasitic inductance.

## Features

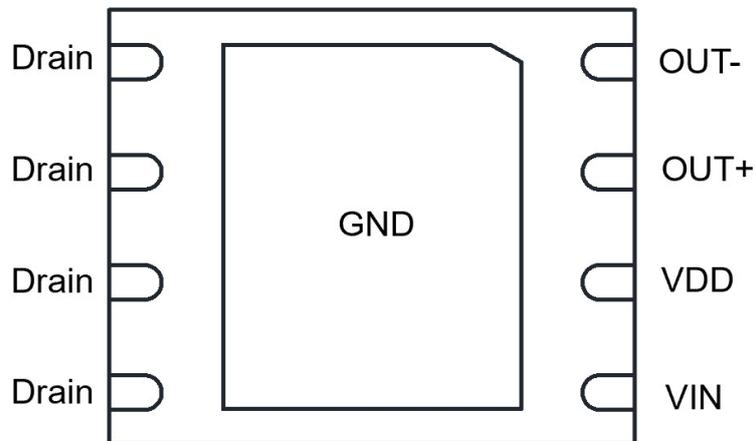
- GaN transistors with integrated gate drive
- 100 V continuous voltage rating
- Zero reverse recovery charge
- Typ./Max.  $R_{DS(ON)} = 5.5/7\text{m}\Omega$
- 7-A pull-up and 5-A pull-down current
- Programmable turn-on dV/dt
- 5 x 6 mm footprint with large cooling pad
- UVLO and over-temperature protection
- Recommended single 5-V supply voltage

## Typical applications

- Automotive LiDAR
- Vehicle Occupant Detection Sensor
- Class-E Wireless Charger
- GaN-Based Synchronous Rectifier
- DC/DC converter
- BLDC driver



## Pin configuration and functions



Package Bottom View

Name	I/O	Description
Drain	P	Drain of GaN transistor.
VDD	P	Gate driver supply voltage. Locally bypass this pin to GND with a ceramic capacitor
VIN	I	PWM signal logic input
OUT+	O	Gate driver turn-on slew-rate set pin (using $R_{gon}$ )
OUT-	O	Gate driver turn-on slew-rate set pin (using $R_{gon}$ )
GND	G	Gate driver ground. Internally connected to Source of GaN transistor

*I = Input, O = Output, P = Power, G = Ground, NC = No Connect*

## Ordering information

Ordering Code	Package	Marking	Packing
CGR1101	DFN5*6	CGR1101	Reel

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## 1 Absolute maximum ratings

Over operating free-air temperature range (unless otherwise noted). Stresses beyond those listed under *Absolute maximum ratings* may cause permanent damage to the device.

Parameters	Sym.	Values			Units	Notes/Test Conditions
		Min.	Typ.	Max.		
Gate driver supply voltage	V <sub>DD</sub>	0	-	5.75	V	
Input pin voltage	V <sub>IN</sub>	-0.3	-	6	V	
OUT+, OUT- pin voltage	V <sub>OUT</sub>	-0.3	-	6	V	
Drain-source voltage	V <sub>DS, max</sub>	-	-	100	V	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 600 μA
Continuous current, drain-source	I <sub>D</sub>	-	-	29	A	T <sub>c</sub> = 25 °C
Pulsed current, drain-source <sup>1</sup>	I <sub>D, pulse</sub>	-	-	125	A	T <sub>c</sub> = 25 °C
Operating temperature	T <sub>j</sub>	-40	-	150	°C	
Storage temperature	T <sub>stg</sub>	-55	-	150	°C	

### Notes

1. Pulse width = 100 μs.

## 2 Recommended operating conditions

Parameters	Sym.	Values			Units	Notes/Test Conditions
		Min.	Typ.	Max.		
Gate driver supply voltage	V <sub>DD</sub>	4.75	5	5.25	V	
Input pin voltage	V <sub>IN</sub>	0	-	V <sub>DD</sub>	V	
OUT+, OUT- pin voltage	V <sub>OUT</sub>	-5	-	V <sub>DD</sub>		
Junction temperature	T <sub>j</sub>	-40	-	+125	°C	

## 3 Thermal characteristics

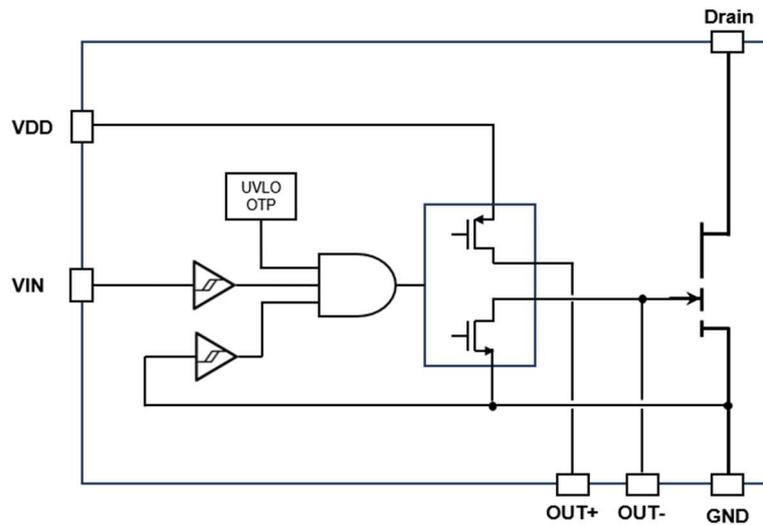
Parameters	Sym.	Values			Units	Notes/Test Conditions
		Min.	Typ.	Max.		
Thermal resistance, junction-case	R <sub>thJC</sub>	-	-	1.6	°C/W	
Reflow soldering temperature	T <sub>sold</sub>	-	-	260	°C	MSL3

## 4 Electrical characteristics

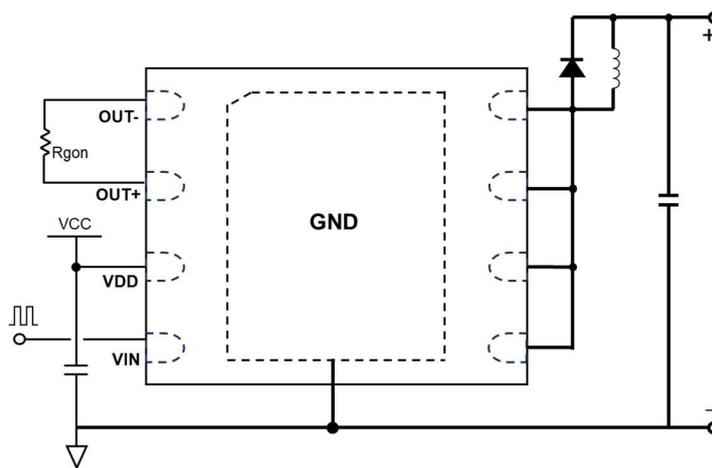
Typical values represent the most likely parametric norm at  $T_j = 25^\circ\text{C}$ , and are provided for reference purposes only.  
Unless otherwise specified,  $V_{DD} = 5\text{ V}$

Parameters	Sym.	Values			Units	Notes/Test Conditions
		Min.	Typ.	Max.		
<b>DC Characteristics</b>						
$V_{DD}$ quiescent current	$I_{VDD,q}$	64	88	128	$\mu\text{A}$	$V_{IN} = 0\text{ V}$
$V_{DD}$ operating current	$I_{VDD,op}$	-	5	-	$\text{mA}$	$f_{sw} = 1\text{ MHz}$ ; $V_{DS} = \text{open}$
Under-voltage Lockout	$V_{DD,UVLO}$	3.9	4.1	4.2	$\text{V}$	
$V_{DD}$ UVLO hysteresis	$V_{DD-HYS}$	-	200	-	$\text{mV}$	
Over temperature shutdown threshold	$T_{OTP}$	-	164	-	$^\circ\text{C}$	
Over temperature hysteresis	$V_{OTP-HYS}$	-	20	-	$^\circ\text{C}$	
<b>Input DC Characteristics</b>						
Input logic high threshold (rising edge)	$V_{IH}$	1.6	-	2.5	$\text{V}$	
Input logic low threshold (falling edge)	$V_{IL}$	1.1	-	1.9	$\text{V}$	
Input logic hysteresis	$V_{IHYS}$	0.4	-	0.9	$\text{V}$	
Input pin pull-down resistance	$R_{IN}$	100	180	200	$\text{k}\Omega$	To GND
<b>Output DC Characteristics</b>						
Peak source current	$I_{OH}$	-	7	-	$\text{A}$	
Peak sink current	$I_{OL}$	-	5	-	$\text{A}$	
<b>Switching Characteristics</b>						
Startup Time, $V_{DD}$ rising above UVLO	$T_{start}$	40	50	70	$\mu\text{s}$	$V_{IN} = V_{DD}$ , $V_{DD}$ rising above 4.4V to OUT+ rising
Turn-on propagation delay	$T_{ON}$	2	3.3	4	$\text{ns}$	$V_{IN}$ to OUT+, 220pF load
Turn-off propagation delay	$T_{OFF}$	2	3.3	4	$\text{ns}$	$V_{IN}$ to OUT-, 220pF load
Rise time	$T_R$	-	650	-	$\text{ps}$	0 $\Omega$ series 220pF load
Fall time	$T_F$	-	650	-	$\text{ps}$	0 $\Omega$ series 220pF load
Minimum input pulse width	$T_{min}$	-	1.25	-	$\text{ns}$	0 $\Omega$ series 220pF load
<b>GaN FET Characteristics</b>						
Drain-source leakage current	$I_{DSS}$	-	1.5	14	$\mu\text{A}$	$V_{DS} = 80\text{V}$ ; $V_{IN} = 0$ ; $T_j = 25^\circ\text{C}$
Drain-source on-state resistance	$R_{DS(on)}$	-	5.5	7	$\text{m}\Omega$	$V_{IN} = 5\text{V}$ ; $I_D = 16\text{A}$ ; $T_j = 25^\circ\text{C}$
		-	10	-	$\text{m}\Omega$	$V_{IN} = 5\text{V}$ ; $I_D = 16\text{A}$ ; $T_j = 125^\circ\text{C}$
Source-drain reverse voltage	$V_{SD}$	-	1.4	-	$\text{V}$	$V_{IN} = 0\text{ V}$ ; $I_{SD} = 0.5\text{ A}$
Reverse recovery charge	$Q_{rr}$	-	0	-	$\text{nC}$	$I_{SD} = 0.5\text{ A}$ ; $V_{DS} = 50\text{ V}$
Output capacitance	$C_{oss}$	-	220	-	$\text{pF}$	$V_{IN} = 0\text{V}$ ; $V_{DS} = 50\text{V}$ ; $f = 1\text{ MHz}$
Effective output capacitance, energy related	$C_{o(er)}$	-	340	-	$\text{pF}$	$V_{IN} = 0\text{ V}$ ; $V_{DS} = 0\text{ to }50\text{ V}$
Effective output capacitance, time related	$C_{o(tr)}$	-	500	-	$\text{pF}$	
Output charge	$Q_{oss}$	-	25	-	$\text{nC}$	

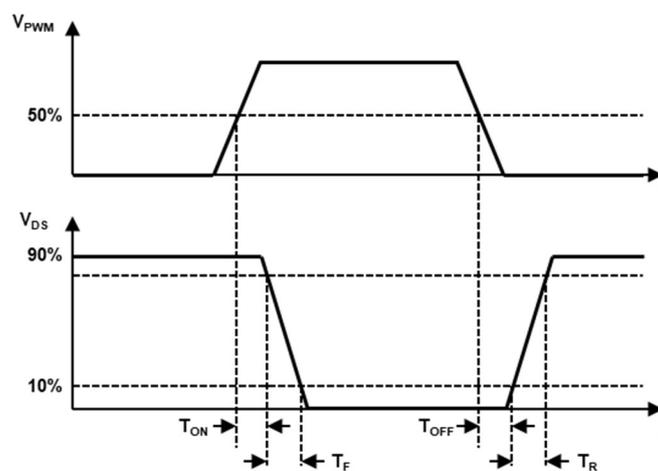
## 5 Block diagram



## 6 Switching waveforms



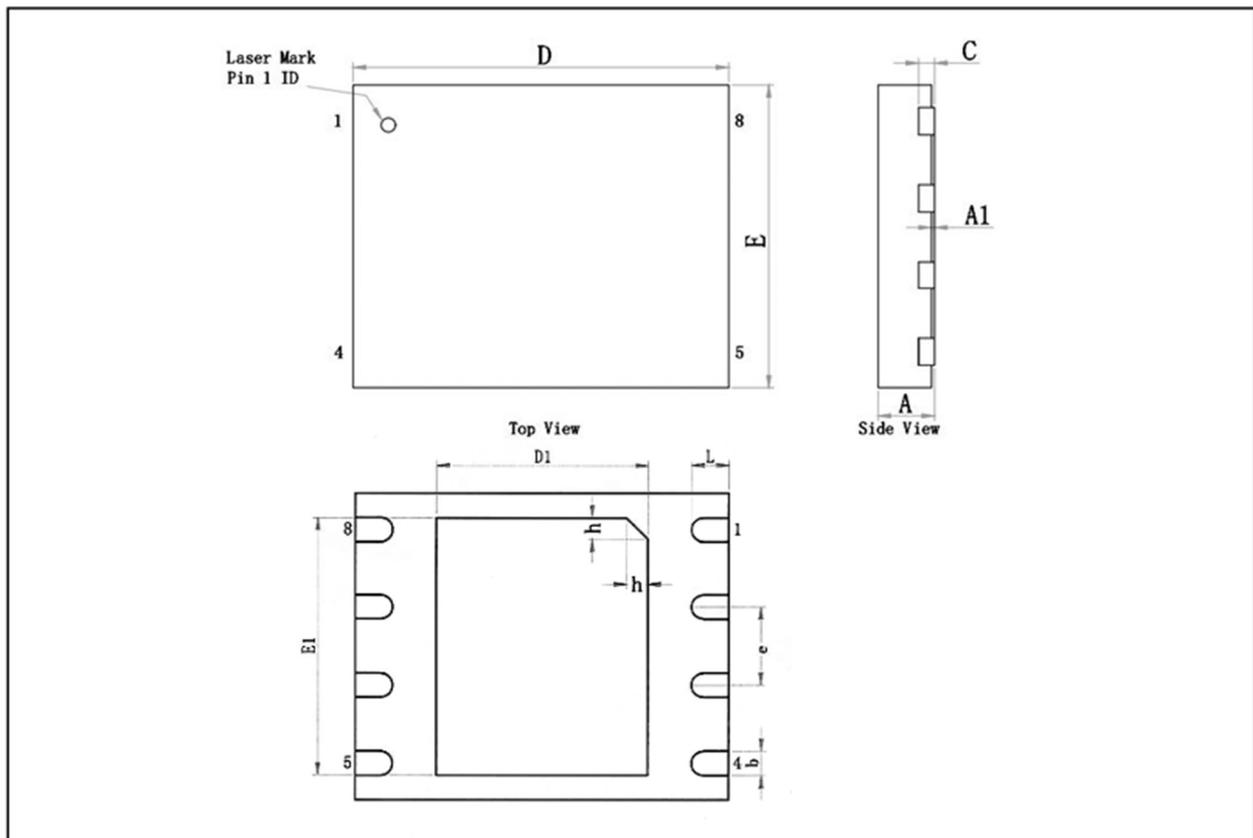
Inductive-load switching circuit



Propagation delay and rise/fall time definitions

## 7 Package outlines

Dimensions(mm)			
Symbol	Min.	Nom.	Max.
A	0.8	0.85	0.9
A1	0.00	0.02	0.05
b	0.35	0.40	0.45
c	0.203REF		
D	5.90	6.00	6.10
D1	3.30	3.40	3.50
E	4.90	5.00	5.10
E1	4.10	4.20	4.30
h	0.30	0.35	0.40
L	0.55	0.60	0.65
e	1.270BSC		



## 8 Revision history

Major changes since the last revision

Revision	Date	Description of changes
1.0	2025-12-3	1.0 version release